What is claimed is:

1. A positive photosensitive resist composition comprising a resin binder and an encapsulated inorganic material.

2. The positive photosensitive resist composition of claim 1, wherein the binder is a t-butyl blocked polyvinyl phenol.

3. The positive photosensitive resist composition of claim 1, wherein the binder is a polyvinylphenol and t-butyl acrylate copolymer.

4. The positive photosensitive resist composition of claim 1, wherein the binder is a polyvinylphenol, t-butyl acrylate and styrene terpolymer.

5. The positive photosensitive resist composition of claim 1, wherein the binder is a DNQ novalak binder.

6. The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material is silicon dioxide. Silica

7. The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material is aluminum oxide. alumina

8. The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material is titanium dioxide. titania

9. The positive photosensitive resist composition of claim 1, wherein the content of the encapsulated inorganic material is between about 0.1% and about 90% by weight of the positive photosensitive resist composition.

10. The positive photosensitive resist composition of claim 1, wherein the content of the encapsulated inorganic material is between about 5% and about 75% by weight of the positive photosensitive resist composition.

11. The positive photosensitive resist composition of claim 1, wherein the content of the encapsulated inorganic material is between about 20% and about 50% by weight of the positive photosensitive resist composition.

12. The positive photosensitive resist composition of claim 1, wherein the binder and the encapsulated inorganic material form a clear positive photosensitive resist composition.

13. The positive photosensitive resist composition of claim 1, further comprising a surfactant.

14. The positive photosensitive resist composition of claim 1, further comprising a solvent.

15. The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material further comprises core particles having an average size ranging from about 1 nm to about 50 nm.

16. The positive photosensitive resist composition of claim 15, wherein the average size of the particles ranges from about 1 to about 20 nm.

17. The positive photosensitive resist composition of claim 1, wherein the encapsulated inorganic material further comprises core particles having an average size less than about 5 nm.

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